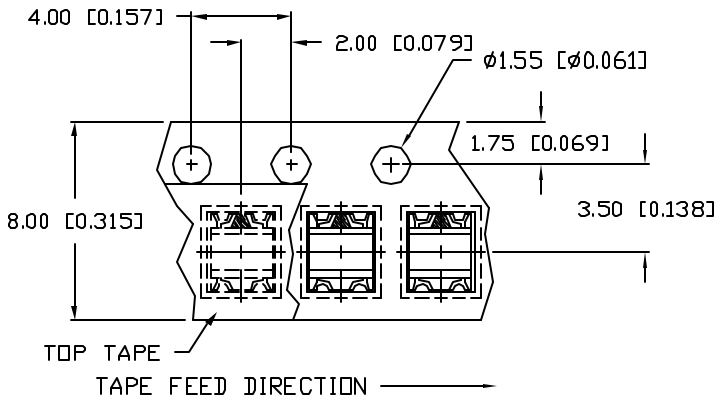
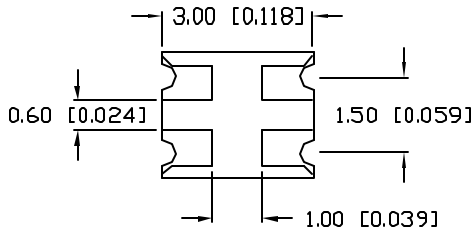
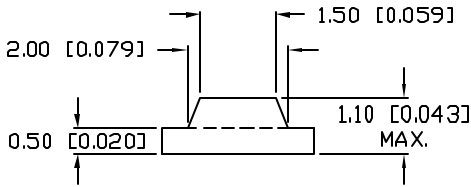
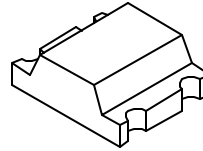
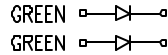
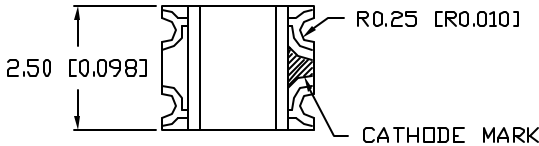
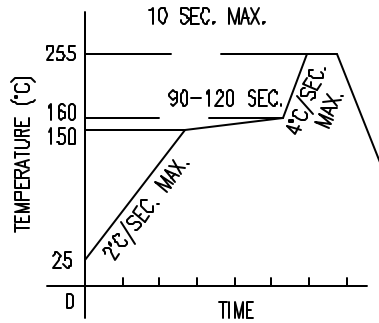


UNCONTROLLED DOCUMENT

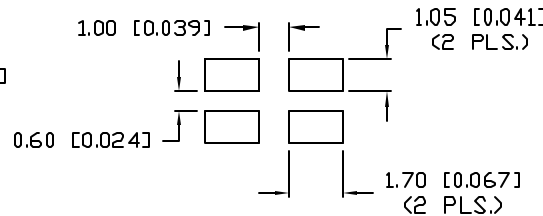


LEAD FREE REFLOW PROFILE



TOTAL TIME ABOVE 220°C IS 60 SECONDS MAX.

RECOMMENDED SOLDER PAD LAYOUT



PART NUMBER
SML-LX2530GGC-TR

REV.
B

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10967.	3.14.03
B	E.C.N. #11148.	7.14.05

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		565 (GREEN)		nm	
		565 (GREEN)		nm	
FORWARD VOLTAGE		2.2	2.6	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_r=100\mu\text{A}$
AXIAL INTENSITY		10		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		160		2x theta	
EMITTED COLOR:	GREEN/GREEN				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	COLORS	MAX	UNITS
PEAK FORWARD CURRENT*		160	mA
STEADY CURRENT		25	mA
POWER DISSIPATION		100	mW
DERATE FROM 25°C		-1.2	mW/°C
OPERATING TEMP.		-30 TO +85	°C
STORAGE TEMP.		-40 TO +85	°C

* $t < 10\mu\text{s}$

NOTES:

1. THE CATHODE IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.



CAUTION: MOISTURE SENSITIVE DEVICE
PER JEDEC LEVEL 4 STANDARDS

UNCONTROLLED DOCUMENT

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.030), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN.=+DECIMAL PRECISION MAX.= -DECIMAL PRECISION

REV. B PART NUMBER SML-LX2530GGC-TR

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3.0mm x 2.5mm SURFACE MOUNT LED, BICOLOR,
DUAL GREEN/GREEN CHIPS,
WATER CLEAR LENS, TAPE AND REEL

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: GT CHECKED BY: APPROVED BY: DATE: 12.22.00
PAGE: 1 OF 1
SCALE: N/A